Light Emitting Diode

Thermal Design Guide for the Nichia NCSU334B (U280) LEDs

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1. Overview

The light output of LEDs decreases due to the effect of heat generation. When LEDs are operated above the maximum LED junction temperature (T_{JMAX}), the reliability will drop significantly. In order to use the NCSU334B LED with high performance and high reliability, it is important to design the heat dissipation so that the junction temperature (T_J) does not exceed the T_{JMAX} of 110°C. Since the NCSU334B requires a high input power it generates a larger amount of heat.

This application note covers the effect on the T_J when two types of mounted boards are driven with different heat dissipation configurations.

- T_J when one LED is mounted on the board and driven by two different heat dissipation configurations
- T_J when nine LEDs are mounted on the board and driven by three different heat dissipation configurations

2. T_J Measurement Method

The following equation can be used to calculate the T_J.

$T_J = T_S + R_{\theta JS} \times W$

T_J : LED Junction Temperature (°C)

T_S : Soldering Temperature (°C)

$R_{\theta JS}$: Thermal Resistance from Junction to T_S Measurement Point (°C/W)

W : Input Power (W) = I_F(A)×V_F(V)

The specifications of the NCSU334B are as follows:

Symbol	Condition	NCSU334B U280	
		Typ	Max
$R_{\theta JS}$ (°C/W)	-	8.4	9.9
V_F (V)	I_F=350mA	5.5	-

Absolute Maximum Ratings (T_S=25°C):

I_{FMAX} (mA)	500
I_{FPMAX} (mA)	600
T_{opr} (°C)	-10～85
T_{JMAX} (°C)	110

I_F : Forward Current (mA)

I_{FP} : Pulse Forward Current (mA)

I_{FP} conditions : pulse width ≤10ms and duty cycle ≤10%

T_{opr} : Operating Temperature (°C)

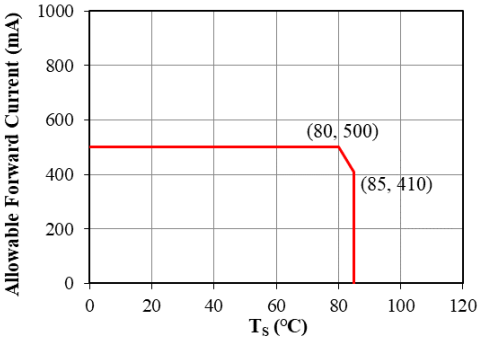


Figure 1. T_S vs Allowable Forward Current

3. T_S Measurement Point

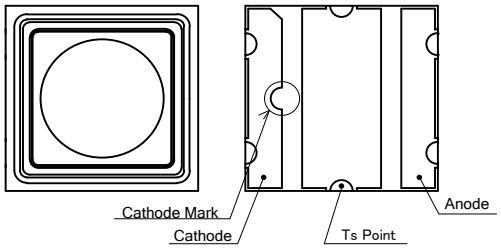


Figure 2. T_S Measurement point

4. Heat Dissipation Configuration and T_J Measurement Results

The T_J was confirmed by changing the heat dissipation configuration when one LED was mounted on the board and when nine LEDs were mounted.

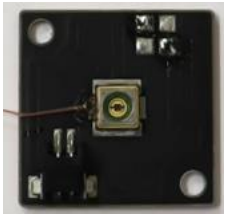
4-1. T_J when one LED is mounted on the board and driven by two different heat dissipation configurations

Heat dissipation configuration 4-1-1, One LED on the board + Heatsink A

The specification of the board is as follows:

Thickness(mm)			Outline dimensions (mm)
Copper foil	Insulation layer	Copper base	
0.105	0.120	1.5	30 × 30

The thermal conductivity of the copper foil and copper base is 390W/m·K and that of the insulation layer is 4.5W/m·K.



Picture 1. Board appearance

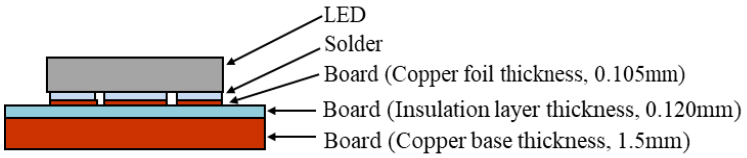


Figure 3. Structure of the board + LED

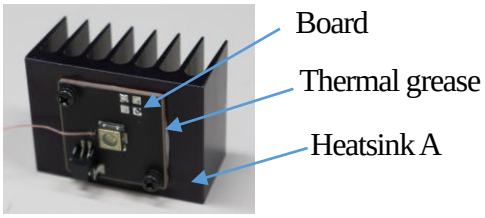
The specification of heatsink A is as follows:

Heatsink A			Fin			Thermal resistance (°C/W)
Material	Size (mm)	Thickness of the base Material (mm)	Number of fins	Size (mm)	Arrangement	
Al	50 × 38 × t25	5	8	1 × 38	8 × 1	5.70

Thermal conductivity of thermal grease is 5.3W/m·K.

The measurement results for the above combinations are shown in the table below:

T_A (°C)	Part number	Wavelength Rank	I_F (A)	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	5.3	1.9	44	62
			0.50	5.4	2.7	52	79



Picture 2. Evaluated light source 4-1-1

With heat dissipation configuration 4-1-1, there was enough margin to not exceed the T_{JMAX} even when 0.50A was applied.
Nichia performed another evaluation where the size of the heatsink was increased.

Heat dissipation configuration 4-1-2, One LED on the board + Heatsink B

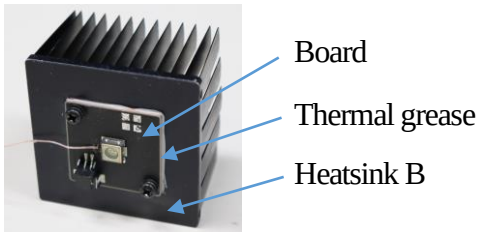
The specification of heatsink B is as follows:

Heatsink B			Fin			Thermal resistance (°C/W)
Material	Size (mm)	Thickness of the base Material (mm)	Number of fins	Size (mm)	Arrangement	
Al	53 × 53 × t35	4	64	0.8 × 9	13 × 5	4.25

Thermal conductivity of thermal grease is 5.3W/m·K.

The results of the evaluation with heatsink B are shown below:

T_A (°C)	Part number	Wavelength Rank	I_F (A)	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	5.3	1.9	36	54
			0.50	5.5	2.8	40	67



Picture 3. Evaluated light source 4-1-2

By increasing the size of the heatsink from A to B, the heat dissipation performance was improved and the T_J was further lowered.

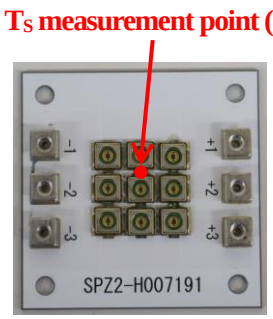
4-2. T_J when nine LEDs are mounted on the board and driven by three different heat dissipation configurations

Heat dissipation configuration 4-2-1, nine LEDs on the board + Heatsink C

The specification of the board is as follows:

Thickness(mm)			Outline dimensions (mm)	Internal circuit	LED mounting pitch (mm)
Copper foil	Insulation layer	Copper base			
0.035	0.120	1.5	60 × 60	3 series, 3 parallel	8.2

The thermal conductivity of the copper foil and copper base is 390W/m·K and that of the insulation layer is 4.5W/m·K.



Picture 4. Board appearance and measurements points

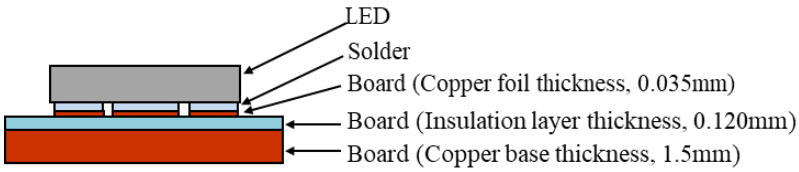


Figure 4. Structure of the board + LED

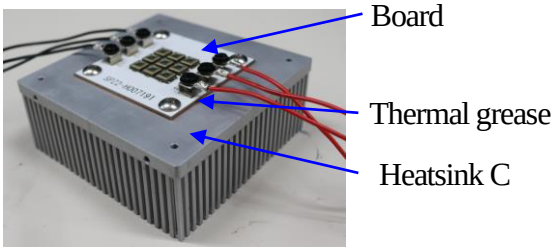
The specification of heatsink C is as follows:

Heatsink C			Fin			Thermal resistance (°C/W)
Material	Size (mm)	Thickness of the base Material (mm)	Number of fins	Size (mm)	Arrangement	
Al	100 × 100 × t40	7	625	2 × 2	25 × 25	0.52

Thermal conductivity of thermal grease is 5.3W/m·K.

The measurement results for the above combinations are shown in the table below:

T_A (°C)	Part number	Wavelength Rank	I_F (A)	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	5.0	1.8	77	94
			0.50	5.1	2.6	88	113



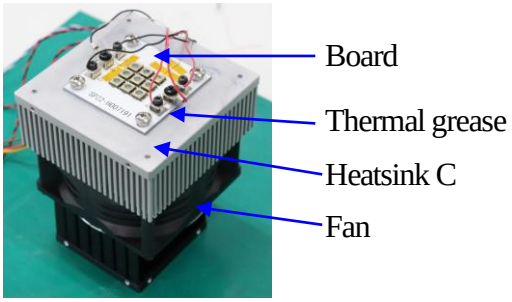
Picture 5. Evaluated light source 4-2-1

In this heat dissipation configuration, the T_J reached 113°C when 0.50A was applied, exceeding the T_{JMAX}.
When mounting LEDs with high density, the temperature rise is too large to be cooled by the heatsink alone, Nichia performed another evaluation using forced air cooling with a fan.

Heat dissipation configuration 4-2-2, nine LEDs on the board + Heatsink with fan (heatsink C with fan attached)

The specification of the fan is as follows:

Fan		
Size (mm)	Volume flow (m^3/min)	Static pressure (Pa)
92 × 92 × t38	5.05	385



Picture 6. Evaluated light source configuration, 4-2-2

The measurement results of the heat dissipation configuration 4-2-1 with a fan attached are shown below:

T_A (°C)	Part number	Wavelength Rank	I_F (A)	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	5.1	1.8	38	56
			0.50	5.3	2.7	44	70

With this heat dissipation configuration, the T_{JMAX} was not exceeded even when 0.50A was applied. By attaching a fan, the heat dissipation is improved and cooling is possible.

Heat dissipation configuration 4-2-3, nine LEDs on the board + Water-cooled Heatsink

The specification of the water-cooled heatsink is as follows:

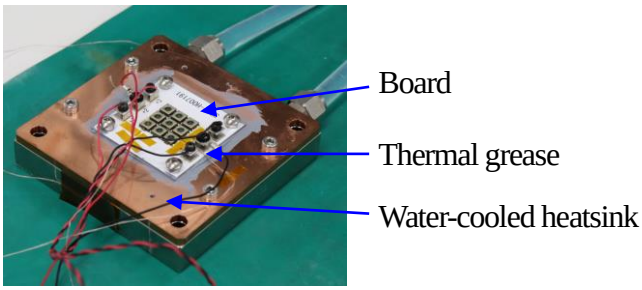
Heatsink		Water temperature (°C)	Water flow rate (L/min)	Thermal resistance (°C/W)
Material	Size (mm)			
Cu	120 × 120 × t25	25	5.6	0.01

Thermal conductivity of thermal grease is 5.3W/m·K.

The measurement results of the board + water-cooled heatsink shown in Picture 7 are shown below:

T_A (°C)	Part number	Wavelength Rank	I_F (A)	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	5.2	1.8	29	47
			0.50	5.3	2.7	31	57

Even with this heat dissipation configuration, when 0.50A was applied, it did not exceed the T_{JMAX} of 110°C. With water cooling, it can be adequately cooled.



Picture 7. Evaluated light source 4-2-3

5. Design Considerations

5-1. Heat Dissipation Performance Depends on the Heatsink Orientation

The performance of naturally air-cooled heatsinks varies depending on the orientation of the fins of the heatsink. Since the T_S will increase when warm air accumulates, it is important that the air movement is not obstructed. At Nichia, the fins are placed to face vertically to allow warm air to escape from the top (See Figure 5).

When designing the system, pay attention to the orientation of the fins when installing the heatsink.

Picture 8.
Fins facing vertical
(Nichia uses this orientation)

Picture 9.
Fins facing down
(This orientation obstructs the air flow)

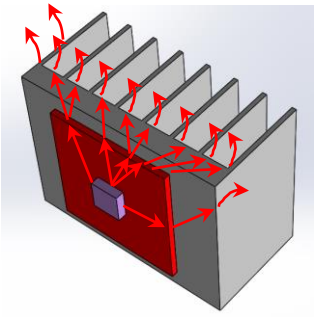
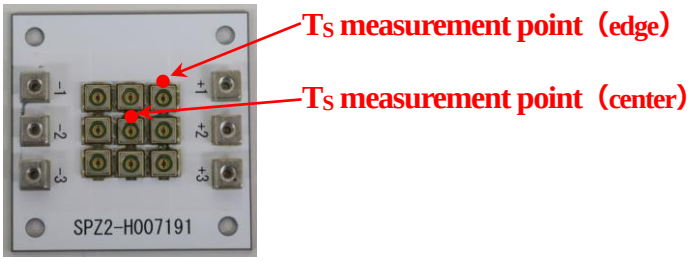


Figure 5.
Image of the heat path when fins are facing vertical

5-2. Heat Dissipation Performance Depends on the Mounted Position when Multiple LEDs are Used

When multiple LEDs are mounted, the T_S varies depending on the mounting pitch and position. As an example, Nichia compared the T_S and T_J between the center and the edge of the LEDs when nine LEDs were mounted in heat dissipation configuration 4-2-2. The results are shown below.



Picture 10. T_S measurement position of an LOB with nine LEDs

Heat dissipation configuration 4-2-1, nine LEDs on the board + Heatsink C

T_A (°C)	Part number	Wavelength Rank	I_F (A)	T_S measurement point	V_F (V)	W (W)	T_S (°C)	T_J (°C)
25	NCSU334B	U280	0.35	center	5.0	1.8	77	94
				edge	5.0	1.8	58	75
			0.50	center	5.1	2.6	88	113
				edge	5.1	2.6	84	109

According to these results, the T_J is slightly lower for the LEDs at the edges than for the LEDs in the center. Therefore, the LED in the center position should be used to measure the T_S for the thermal design since that is where the T_J is the highest.

6. Summary

On a board with one LED, there was sufficient margin to stay under the T_{JMAX}, even with an air-cooling heat dissipation configuration using only a heatsink. Additionally, a larger heatsink size resulted in an even lower T_J.
When mounting multiple LEDs with high density, it is difficult to keep the LEDs within the T_{JMAX} limit with only a heatsink; however, if a fan is attached to the heatsink or if water cooling is used, it is possible to keep the LEDs within the T_{JMAX} limit. For high density configurations, heat interference occurs between adjacent LEDs, resulting in poor heat dissipation, making it necessary to use a sufficient pitch width or use forced air or water cooling.

The absolute maximum ratings for the NCSU334B LED per the Nichia specification:

I_F=0.50A, T_{JMAX}=110°C

Nichia will not guarantee the LEDs if used above these ratings.

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